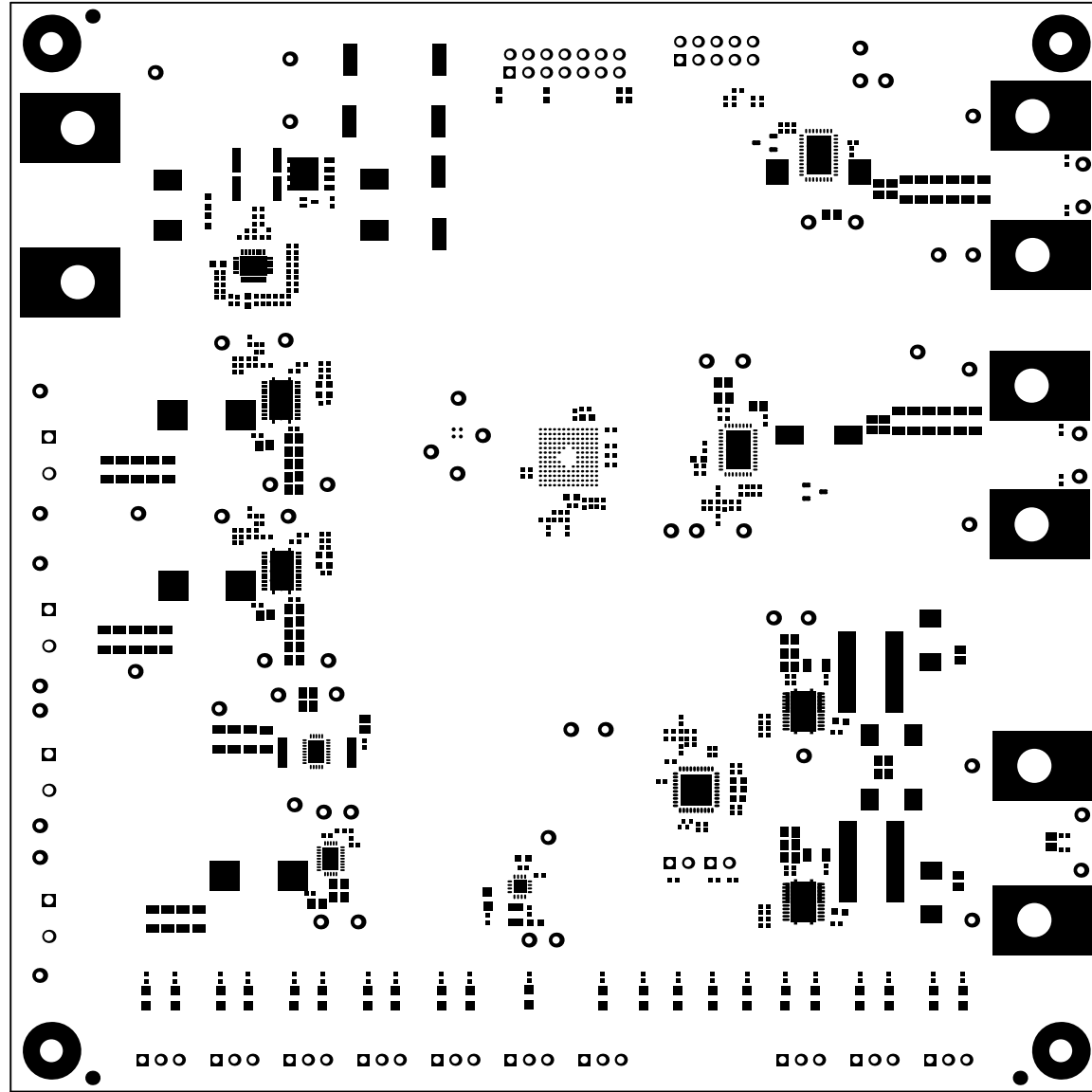
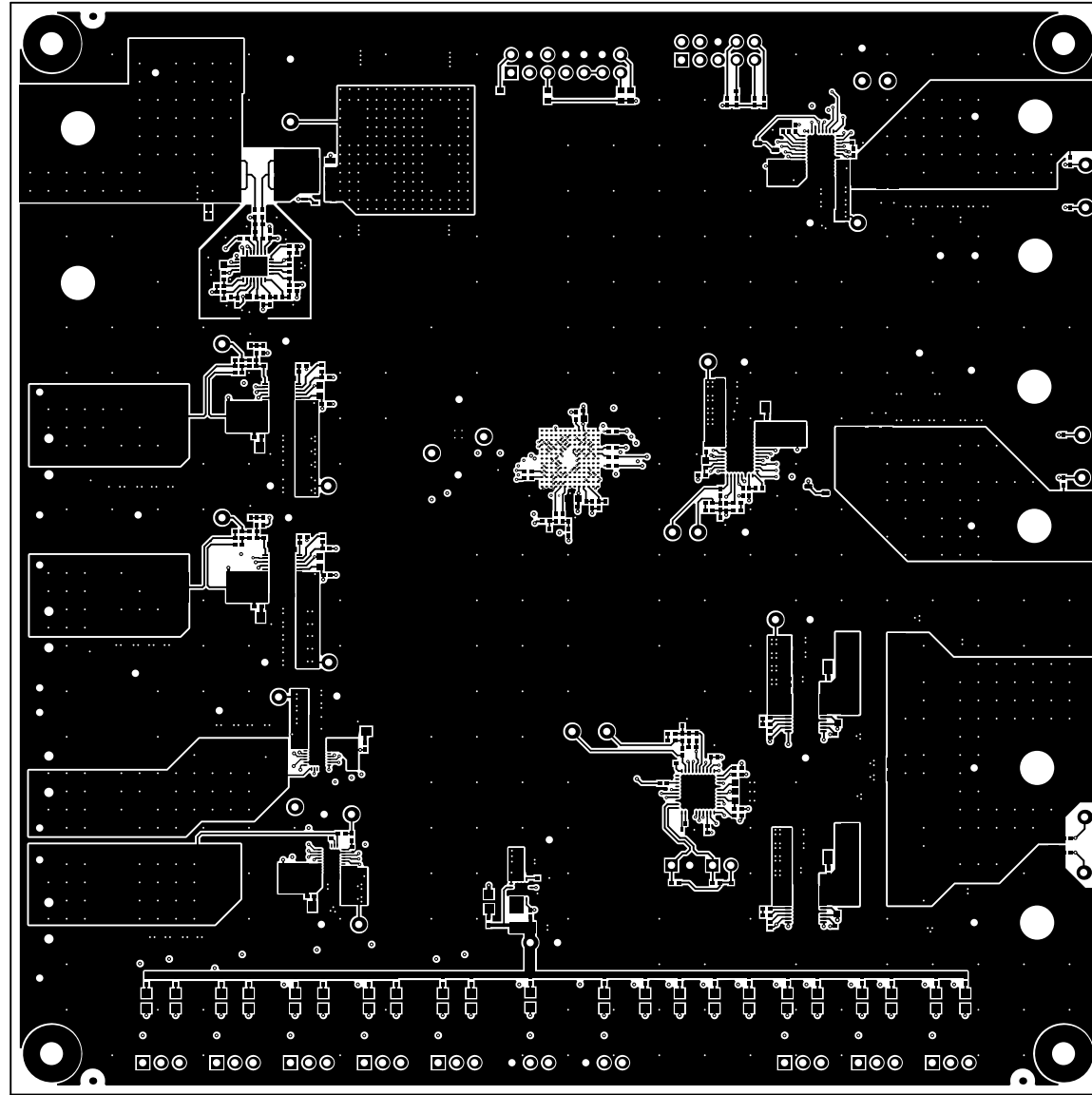


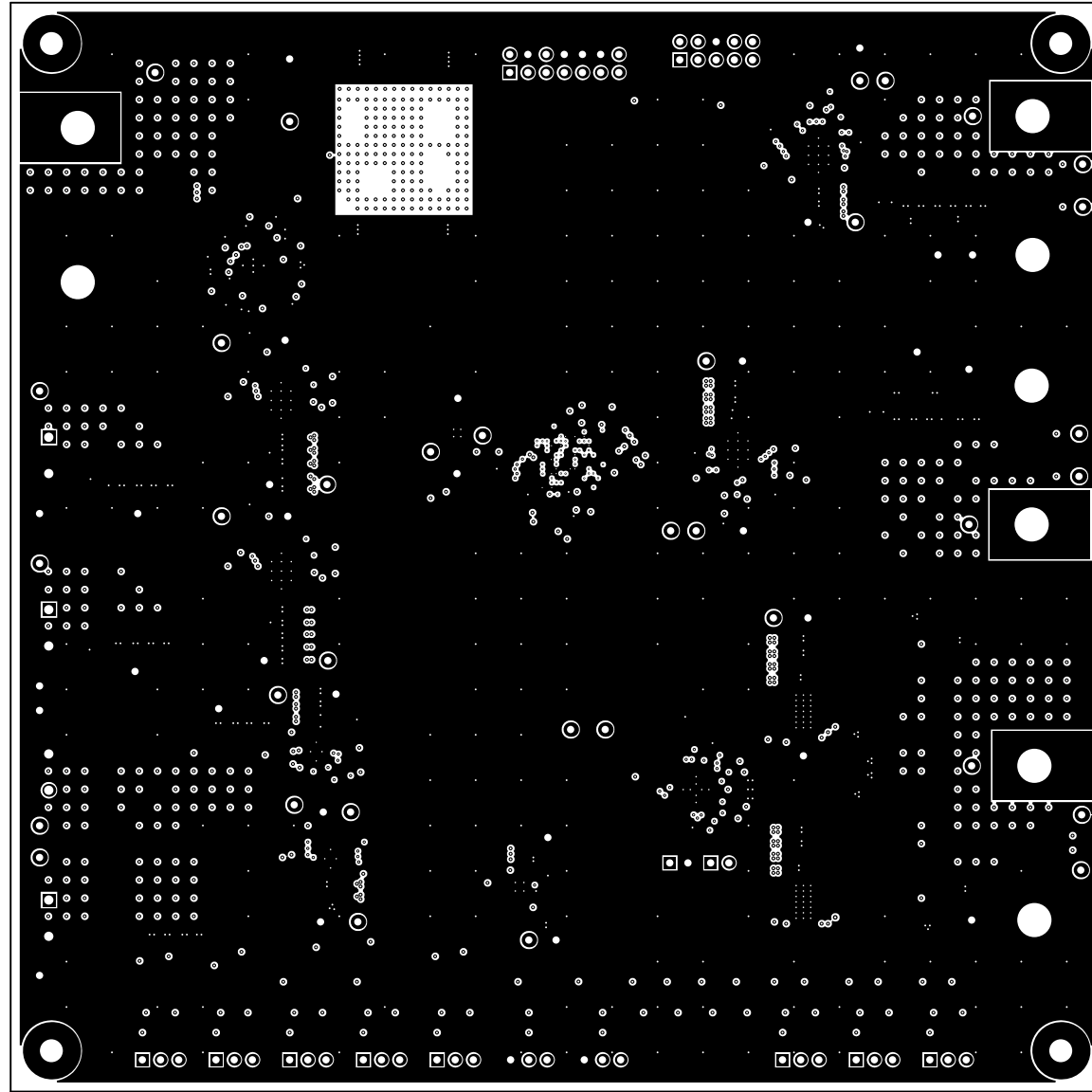
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2/18/2015 8:05:39 AM	TEXAS INSTRUMENTS	



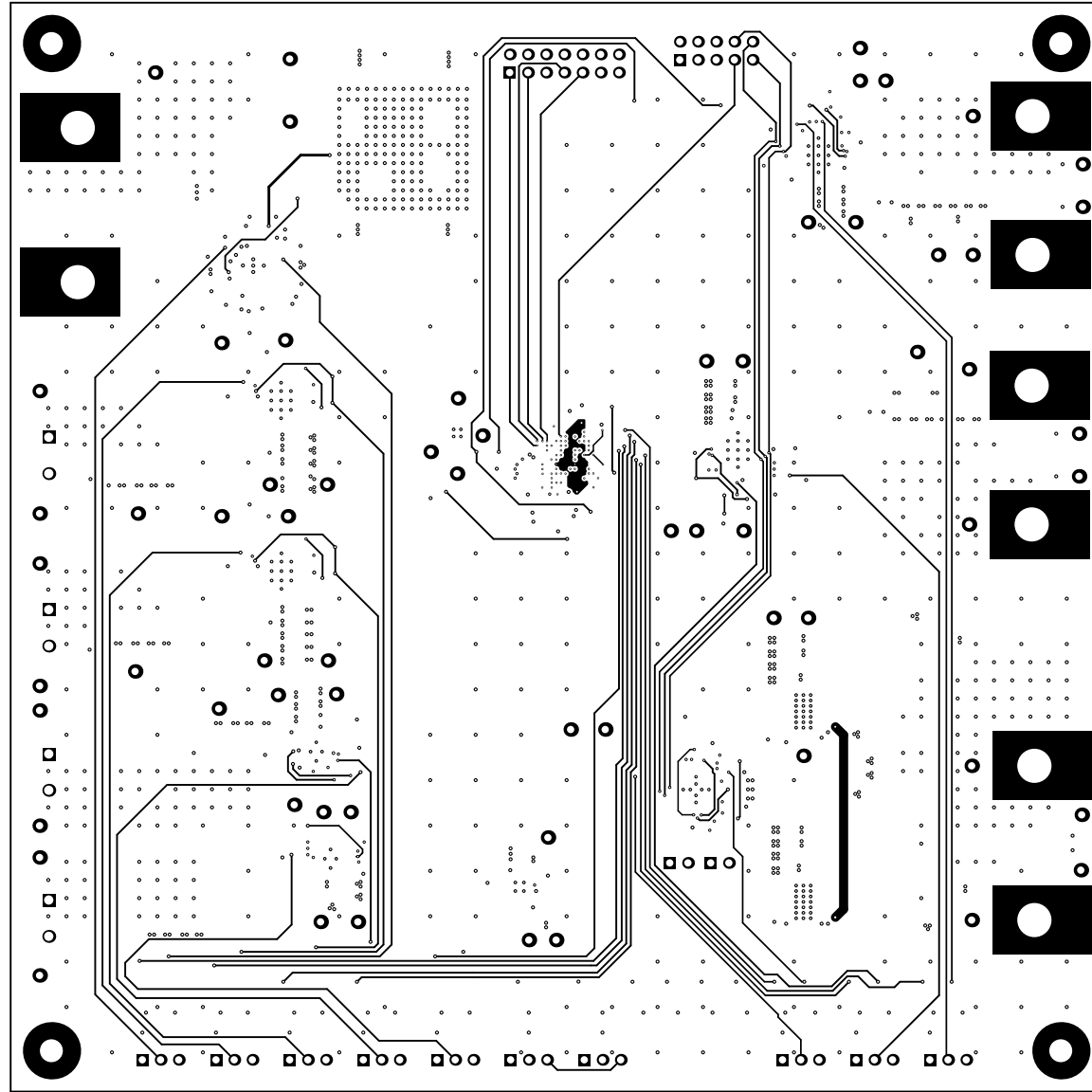
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/18/2015 8:05:40 AM	TEXAS INSTRUMENTS	



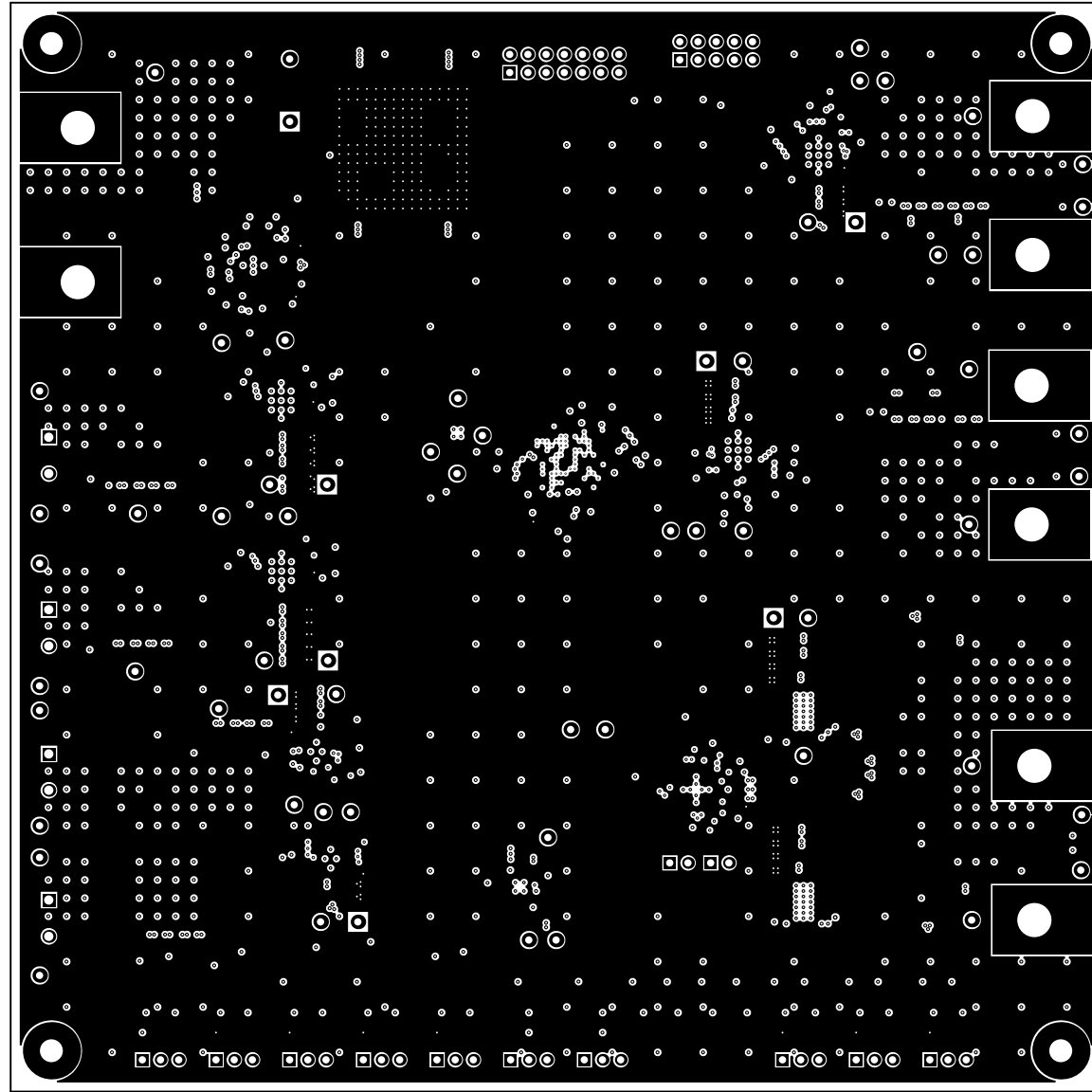
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/18/2015 8:05:41 AM	TEXAS INSTRUMENTS	



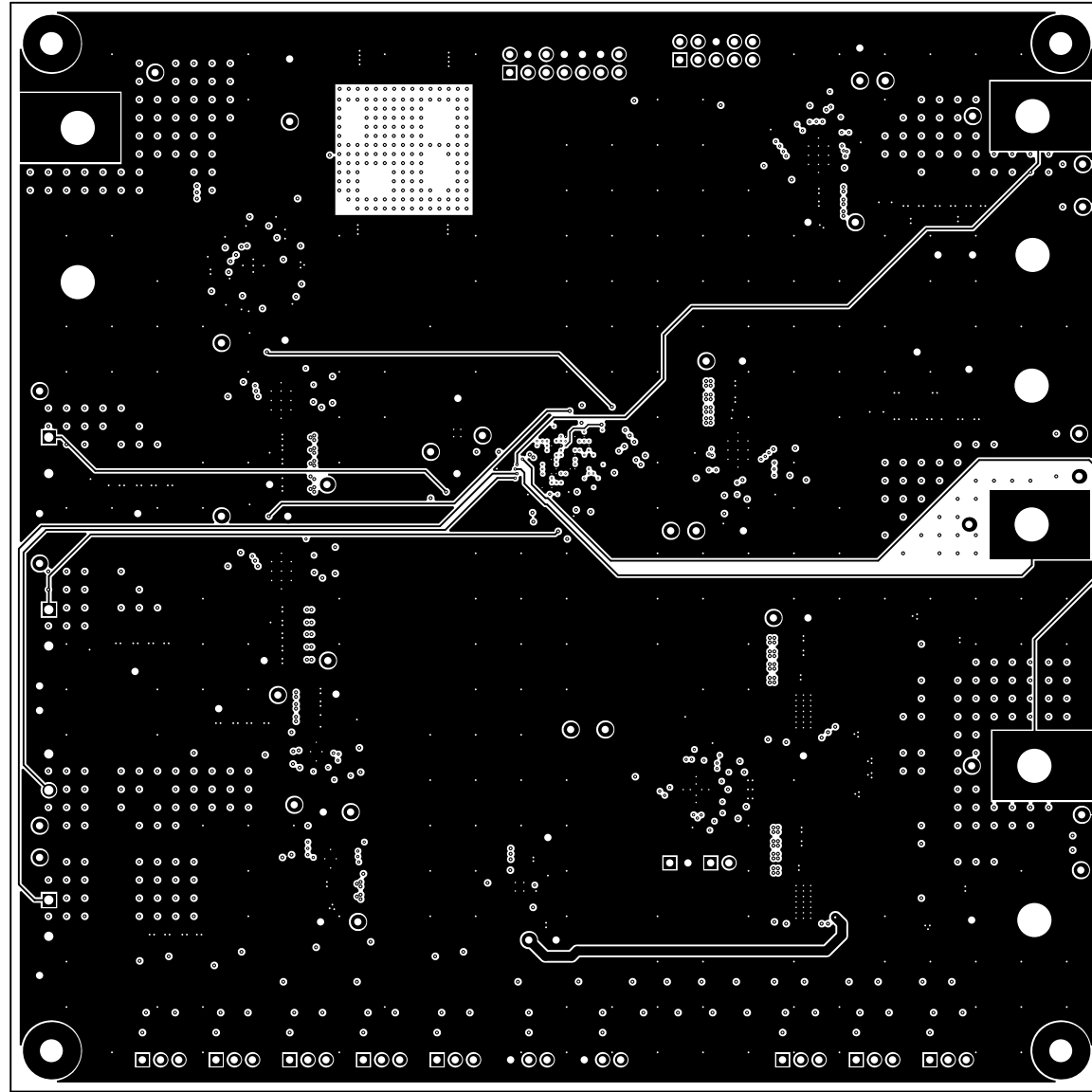
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 1			
PLOT NAME = MidLayer1	GENERATED : 2/18/2015 8:05:41 AM	TEXAS INSTRUMENTS	



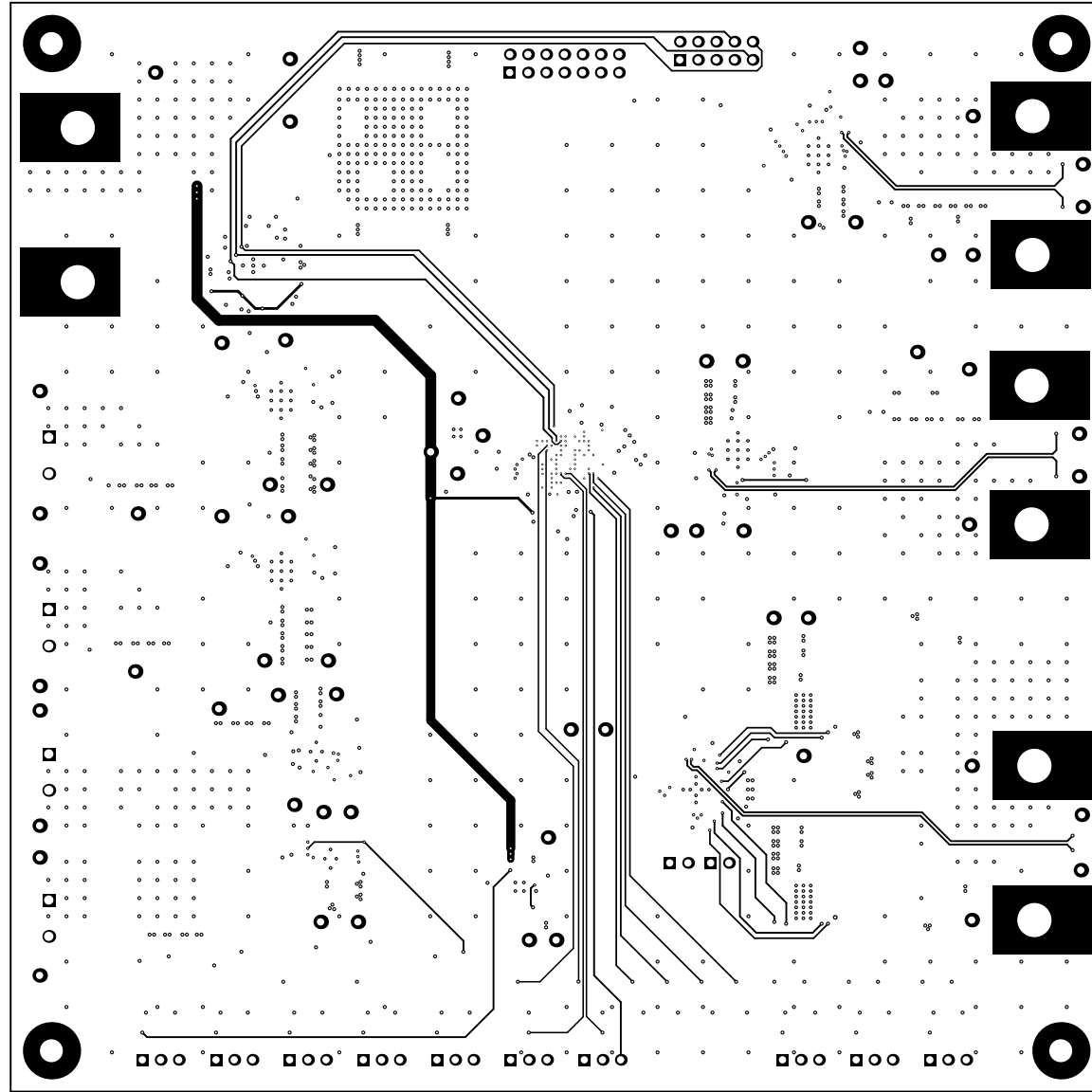
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 2			
PLOT NAME = MidLayer2	GENERATED : 2/18/2015 8:05:42 AM	TEXAS INSTRUMENTS	



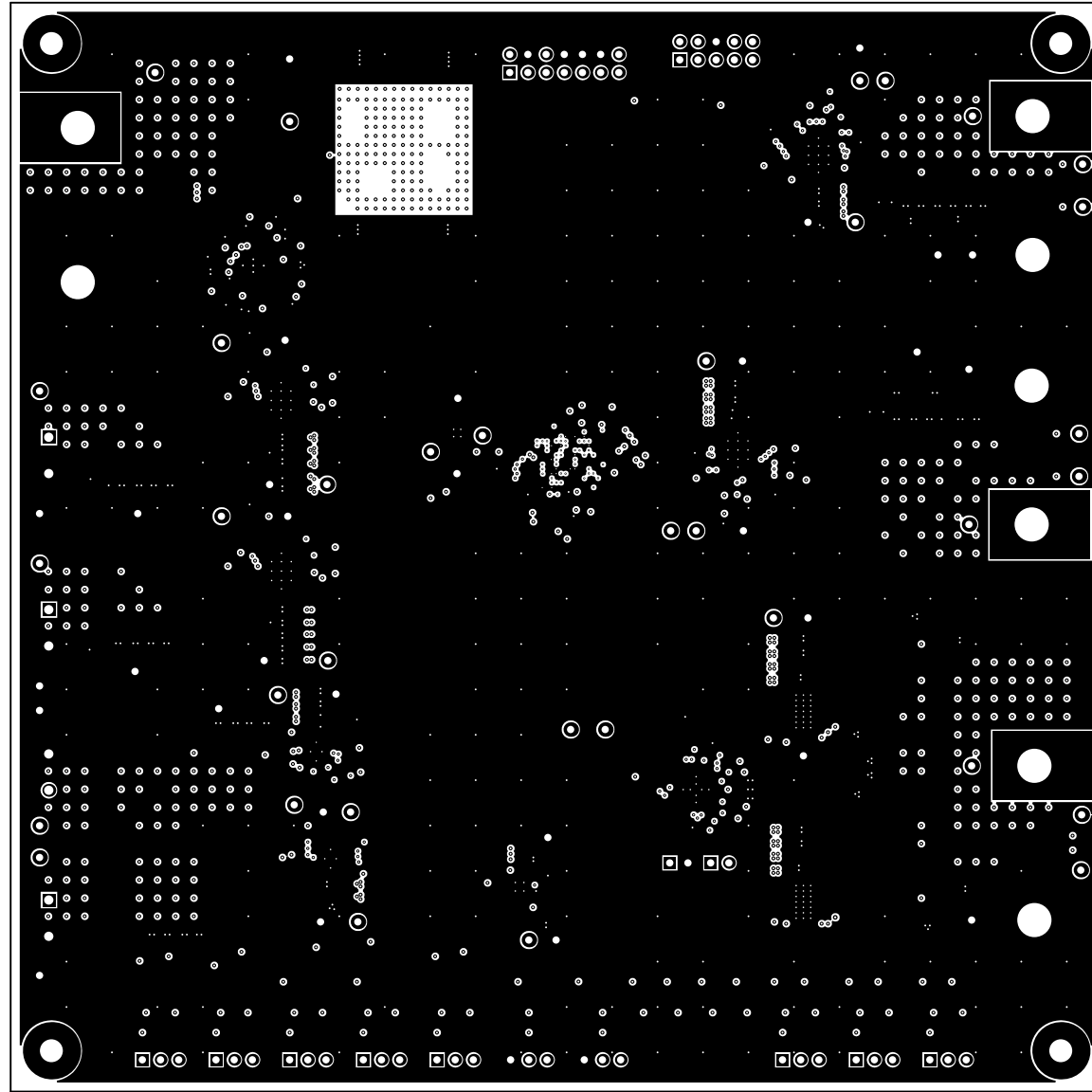
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Mid-Layer 3			
PLOT NAME = MidLayer3	GENERATED : 2/18/2015 8:05:43 AM	TEXAS INSTRUMENTS	



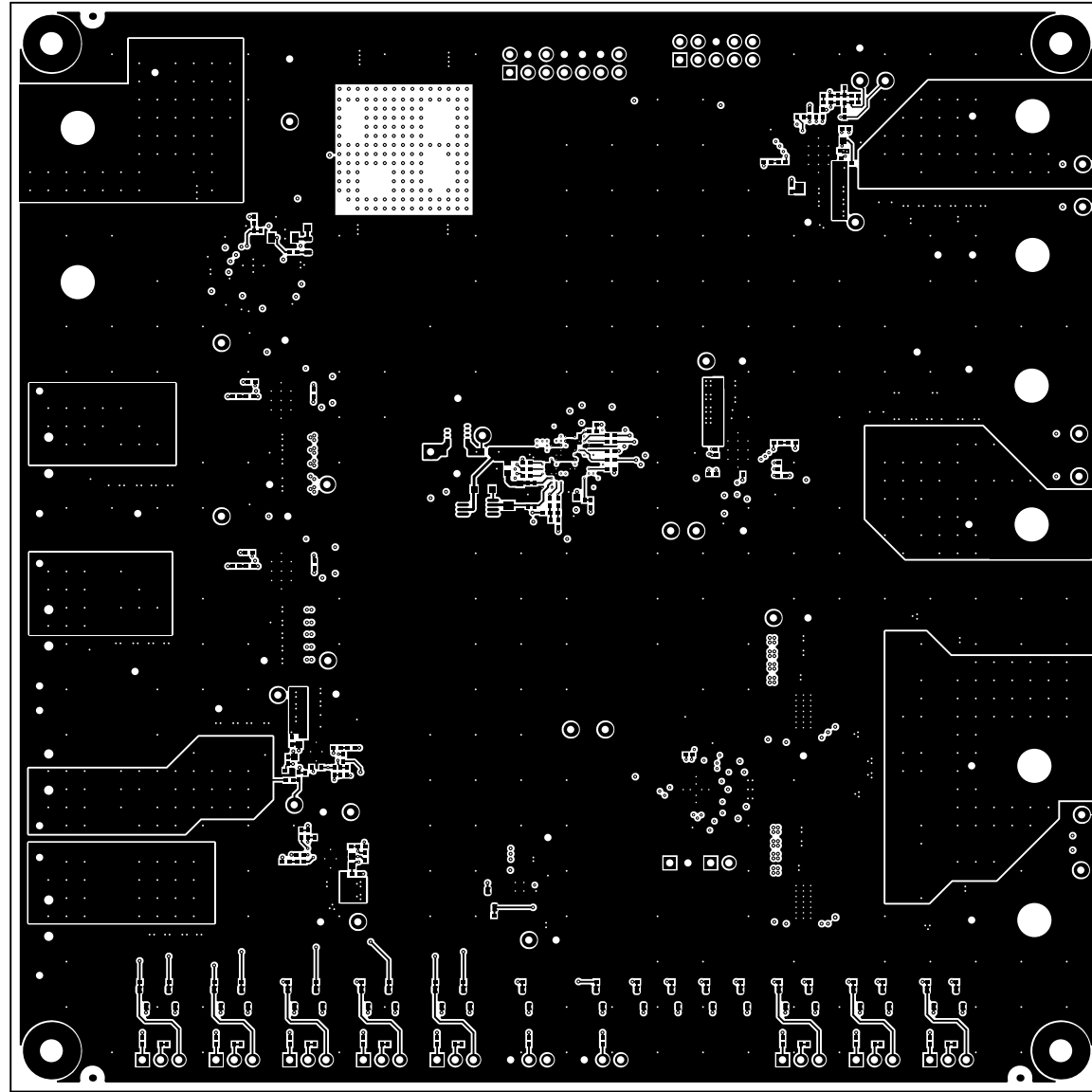
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 4			
PLOT NAME = MidLayer4	GENERATED : 2/18/2015 8:05:43 AM	TEXAS INSTRUMENTS	



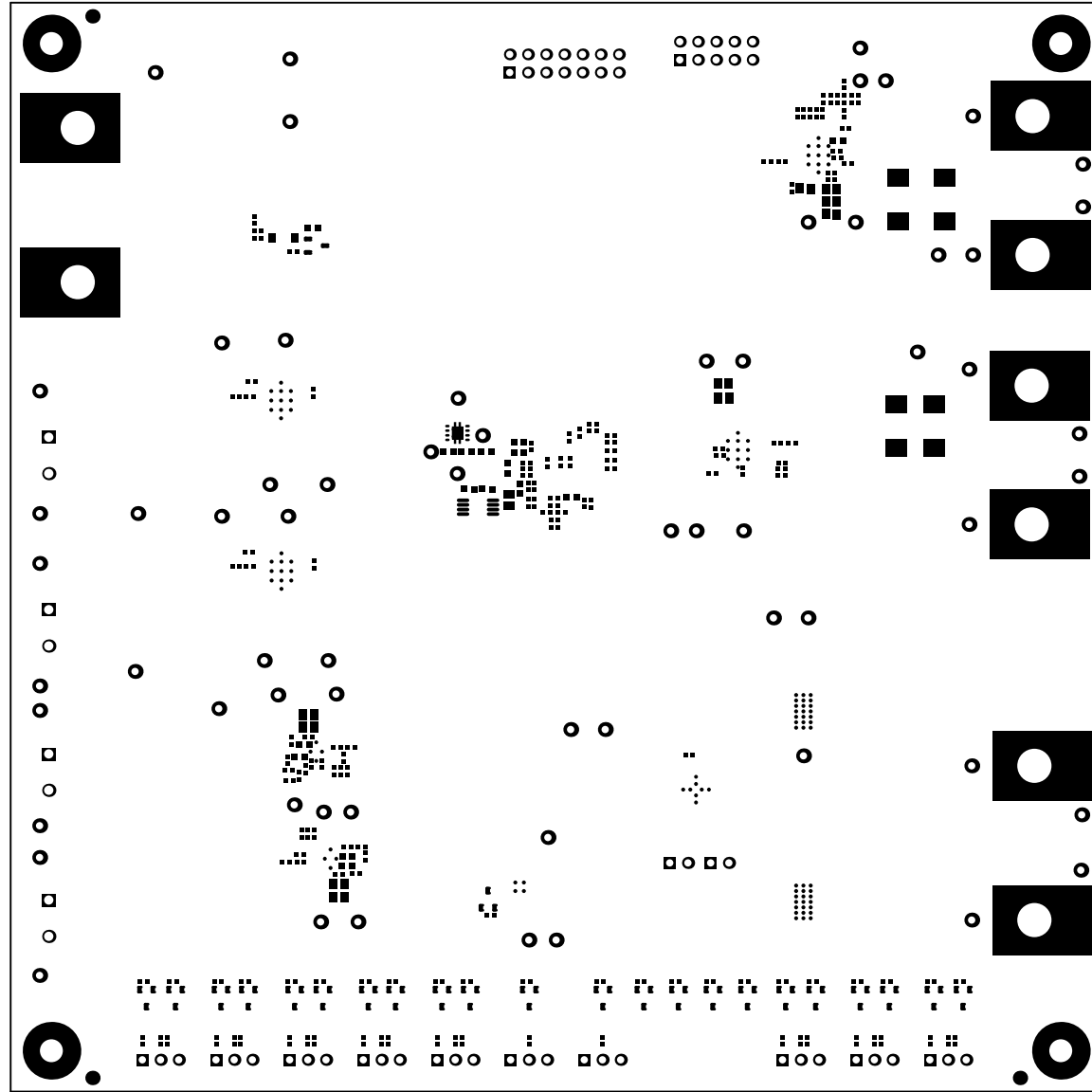
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 5			
PLOT NAME = MidLayer5	GENERATED : 2/18/2015 8:05:44 AM	TEXAS INSTRUMENTS	



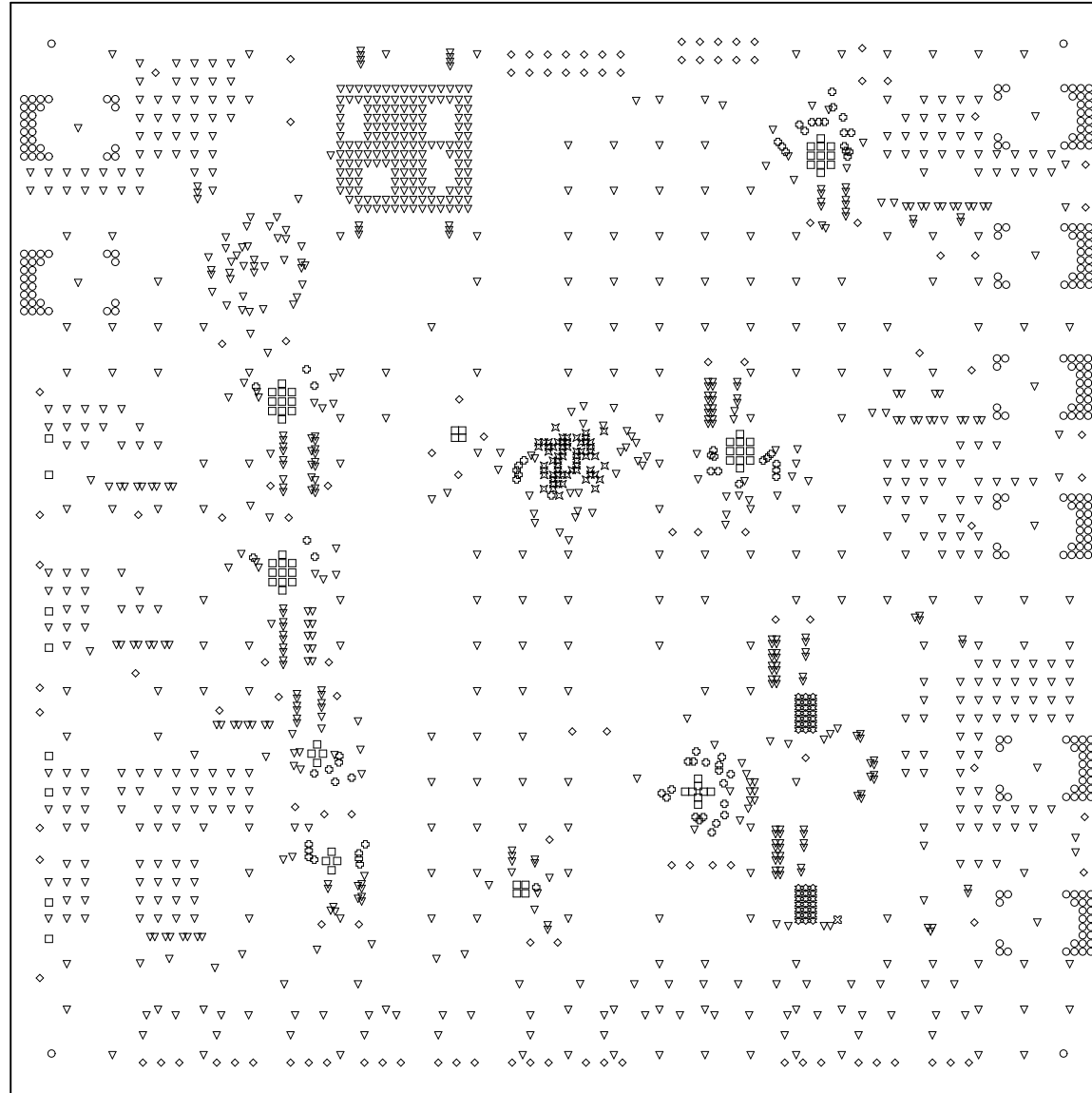
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 6			
PLOT NAME = MidLayer6	GENERATED : 2/18/2015 8:05:44 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/18/2015 8:05:45 AM	TEXAS INSTRUMENTS	



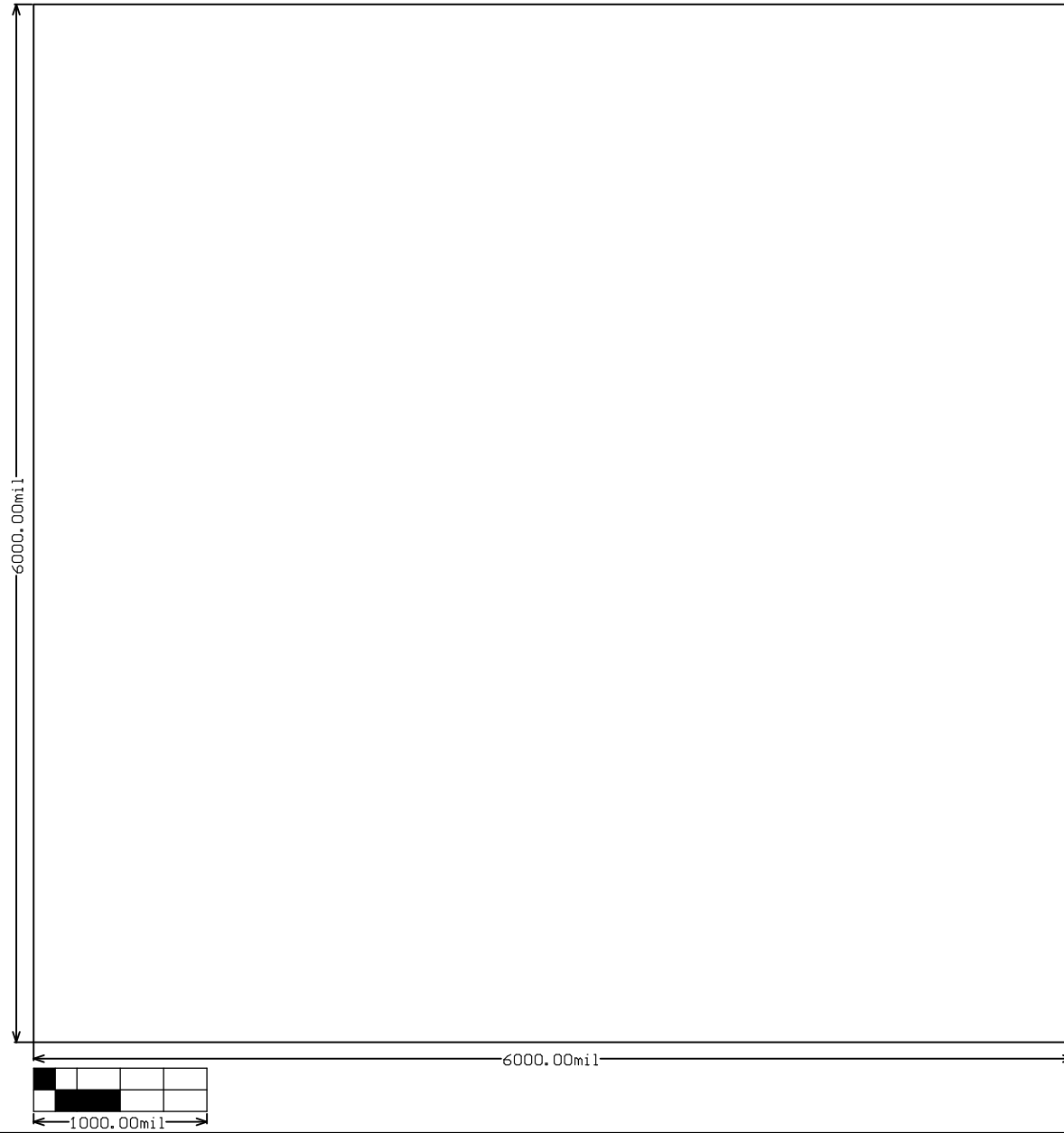
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/18/2015 8:05:46 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
×	61	6mil (0.152mm)	PTH	Round
*	42	7.8mil (0.198mm)	PTH	Round
□	68	7.874mil (0.2mm)	PTH	Round
◇	75	8mil (0.203mm)	PTH	Round
▽	1115	10mil (0.254mm)	PTH	Round
⊗	1	12mil (0.305mm)	PTH	Round
○	224	16mil (0.406mm)	PTH	Round
◇	123	40mil (1.016mm)	PTH	Round
□	8	51.181mil (1.3mm)	PTH	Round
○	4	125.984mil (3.2mm)	PTH	Round
▽	8	188mil (4.775mm)	PTH	Round
1729 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/18/2015 8:05:47 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10896	REV: B	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/18/2015 8:05:48 AM	TEXAS INSTRUMENTS	

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